



US009361960B2

(12) **United States Patent**
Vogelsang

(10) **Patent No.:** **US 9,361,960 B2**
(45) **Date of Patent:** **Jun. 7, 2016**

(54) **CONFIGURABLE MEMORY BANKS OF A MEMORY DEVICE**

(75) Inventor: **Thomas Vogelsang**, Mountain View, CA (US)

(73) Assignee: **RAMBUS INC.**, Sunnyvale, CA (US)

(*) Notice: Subject to any disclaimer, the term of this patent is extended or adjusted under 35 U.S.C. 154(b) by 767 days.

(21) Appl. No.: **13/394,533**

(22) PCT Filed: **Aug. 23, 2010**

(86) PCT No.: **PCT/US2010/046269**

§ 371 (c)(1),

(2), (4) Date: **Mar. 6, 2012**

(87) PCT Pub. No.: **WO2011/034686**

PCT Pub. Date: **Mar. 24, 2011**

(65) **Prior Publication Data**

US 2012/0166753 A1 Jun. 28, 2012

Related U.S. Application Data

(60) Provisional application No. 61/243,114, filed on Sep. 16, 2009.

(51) **Int. Cl.**
G06F 12/00 (2006.01)
G11C 8/12 (2006.01)
G11C 7/10 (2006.01)

(Continued)

(52) **U.S. Cl.**
CPC **G11C 8/12** (2013.01); **G11C 7/1012** (2013.01); **G11C 7/1045** (2013.01); **G11C 11/4087** (2013.01); **G11C 11/4096** (2013.01); **G11C 2207/002** (2013.01); **G11C 2207/105** (2013.01)

(58) **Field of Classification Search**

CPC G06F 12/023; G06F 3/067; G06F 9/0516; G06F 3/0631

USPC 711/170
See application file for complete search history.

(56) **References Cited**

U.S. PATENT DOCUMENTS

5,142,638 A * 8/1992 Schifflerger 711/151
5,940,852 A 8/1999 Rangasayee et al.
6,049,223 A 4/2000 Lytle et al.

(Continued)

FOREIGN PATENT DOCUMENTS

JP 06-250935 A 9/1994
JP 2008-084052 A 4/2008
JP 2008-112503 A 5/2008

OTHER PUBLICATIONS

Rambus Inc., International Search Report and Written Opinion, PCT/US2010/046269, Apr. 28, 2010, 8 pages.

Primary Examiner — Charles Rones

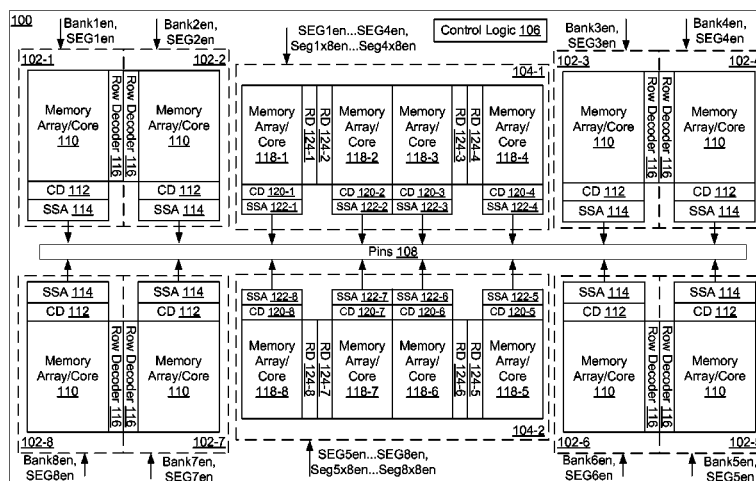
Assistant Examiner — Nanci Wong

(74) *Attorney, Agent, or Firm* — Morgan, Lewis & Bockius LLP

(57) **ABSTRACT**

A memory device has a storage array having a plurality of accessible memory banks and a configurable first set of memory segments. The plurality of accessible memory banks include a second set of memory segments. During a first mode of operation, the first set of memory segments is configured to be an additional accessible memory bank. During a second mode of operation, a pair of memory segments in the first set of memory segments are configured to be an additional set of memory segments in each of the plurality of accessible memory banks.

26 Claims, 9 Drawing Sheets



Page 2

* cited by examiner

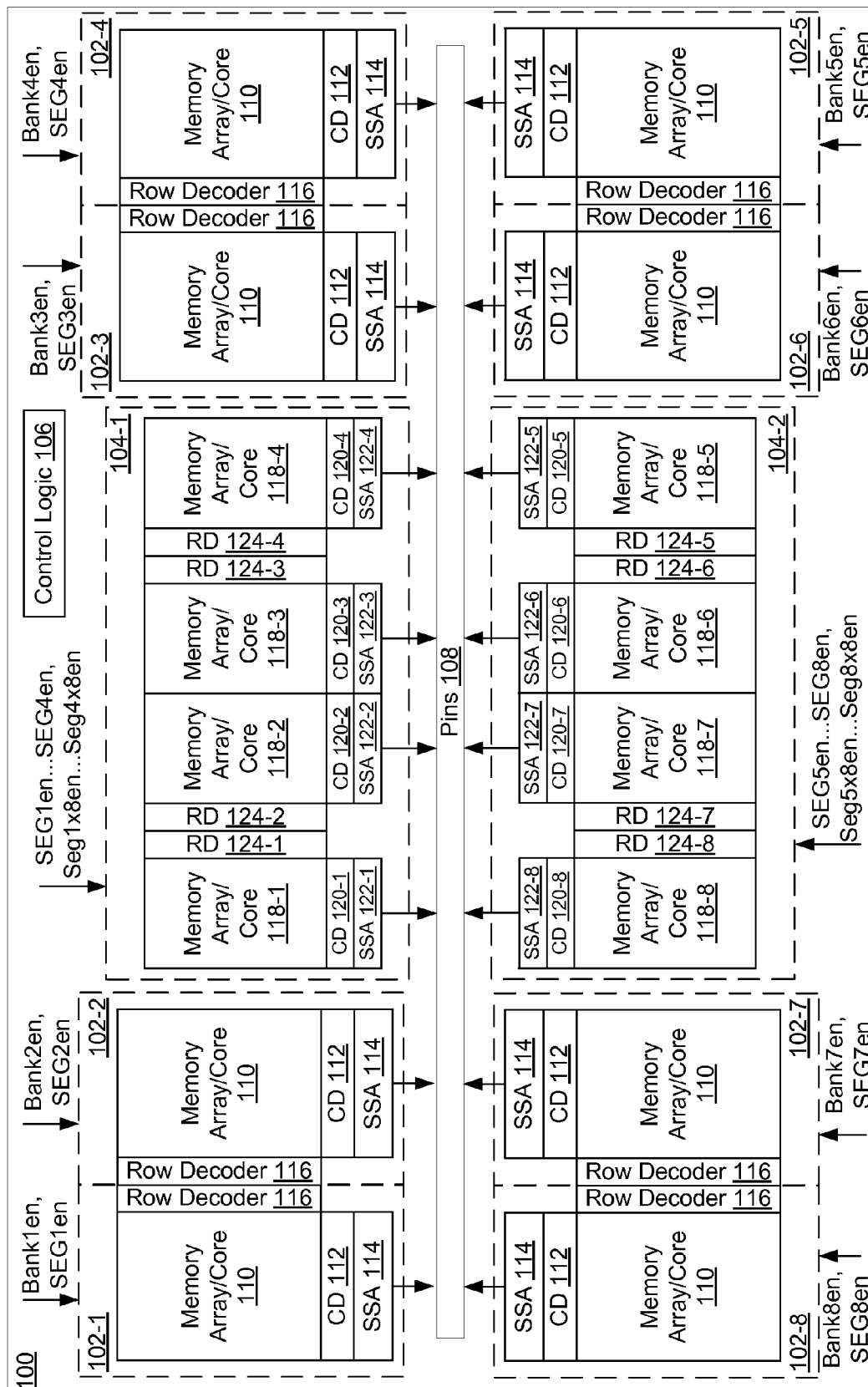


Figure 1

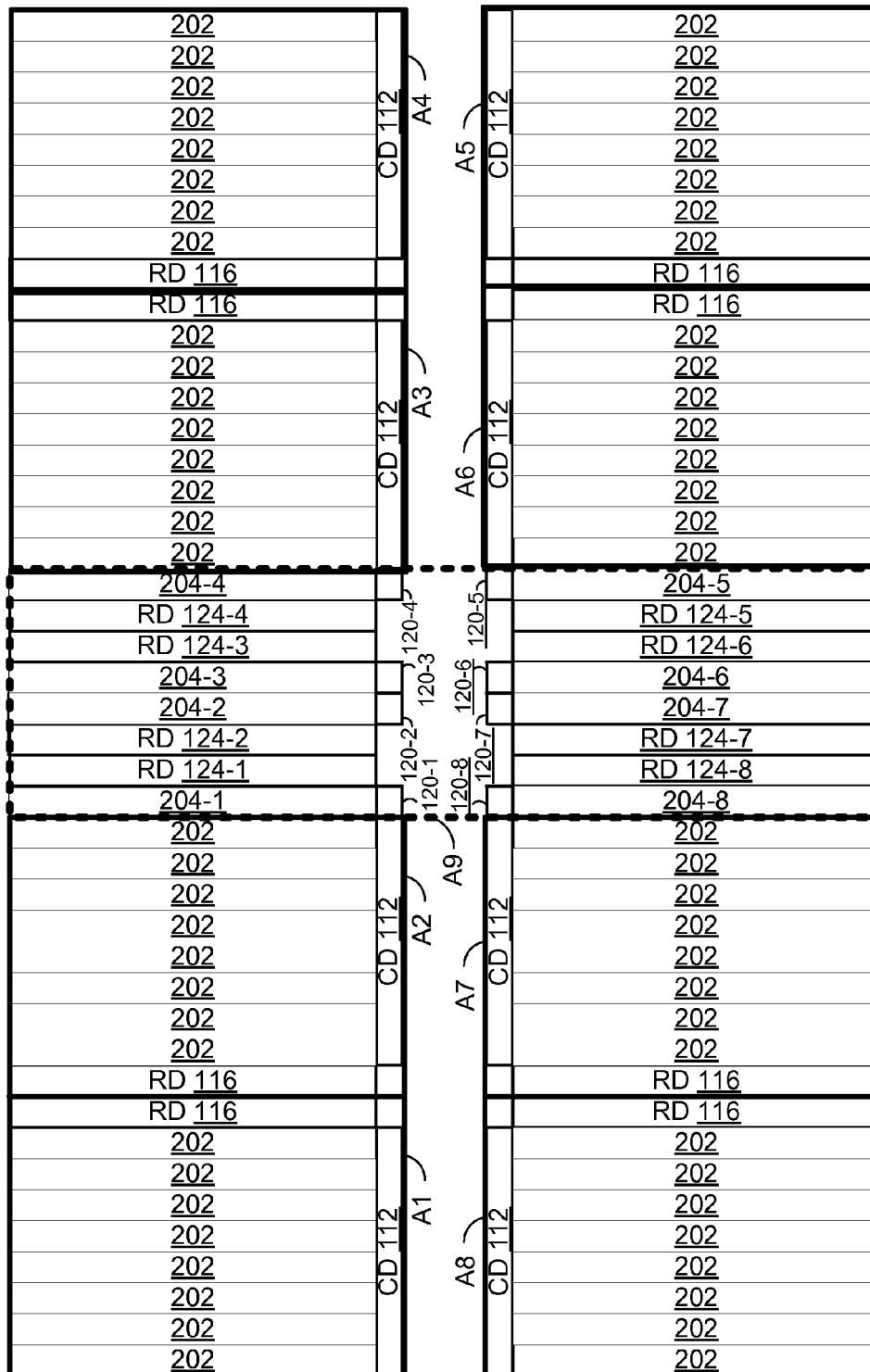


Figure 2A

100x8

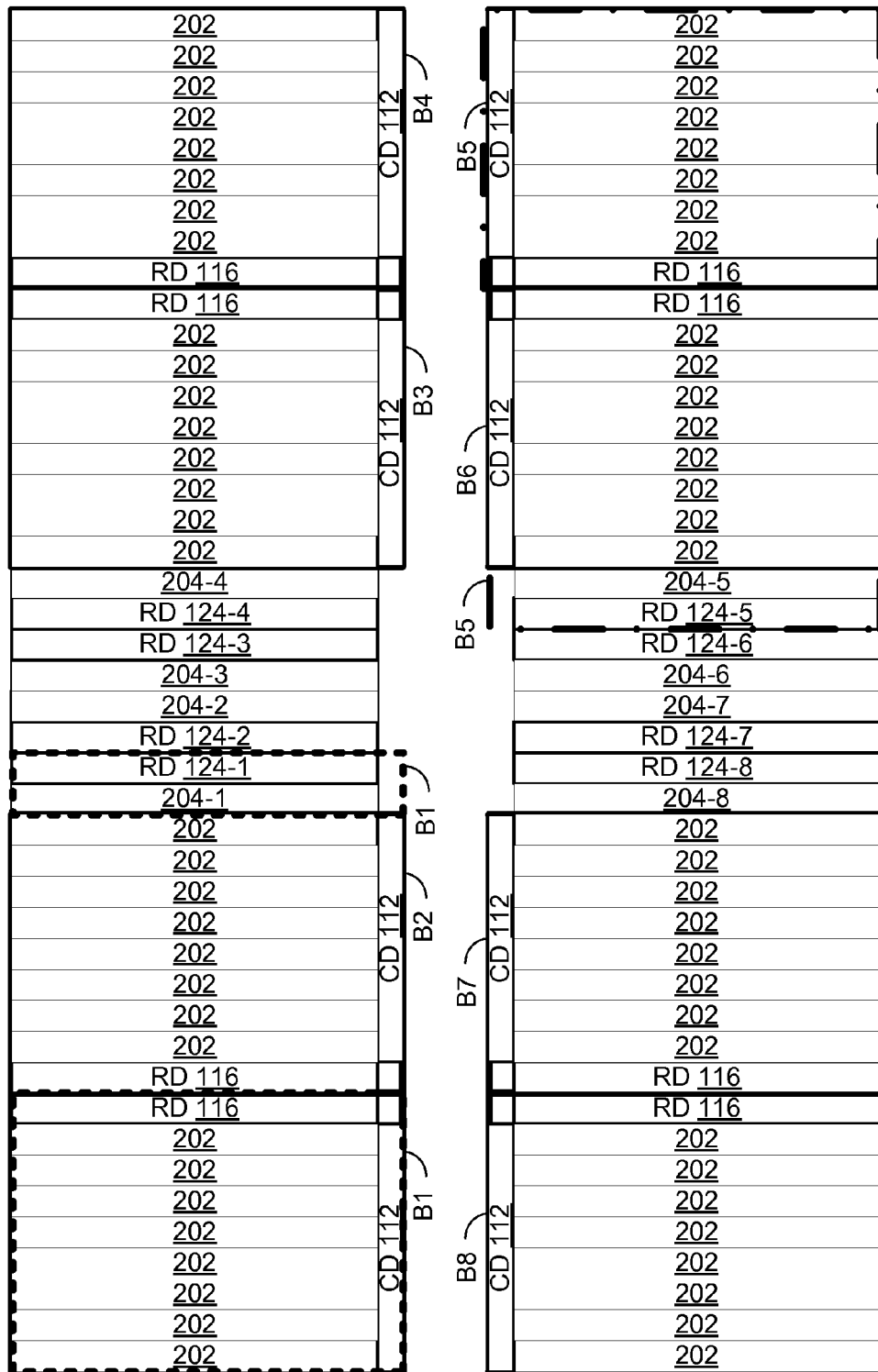


Figure 2B

100x9

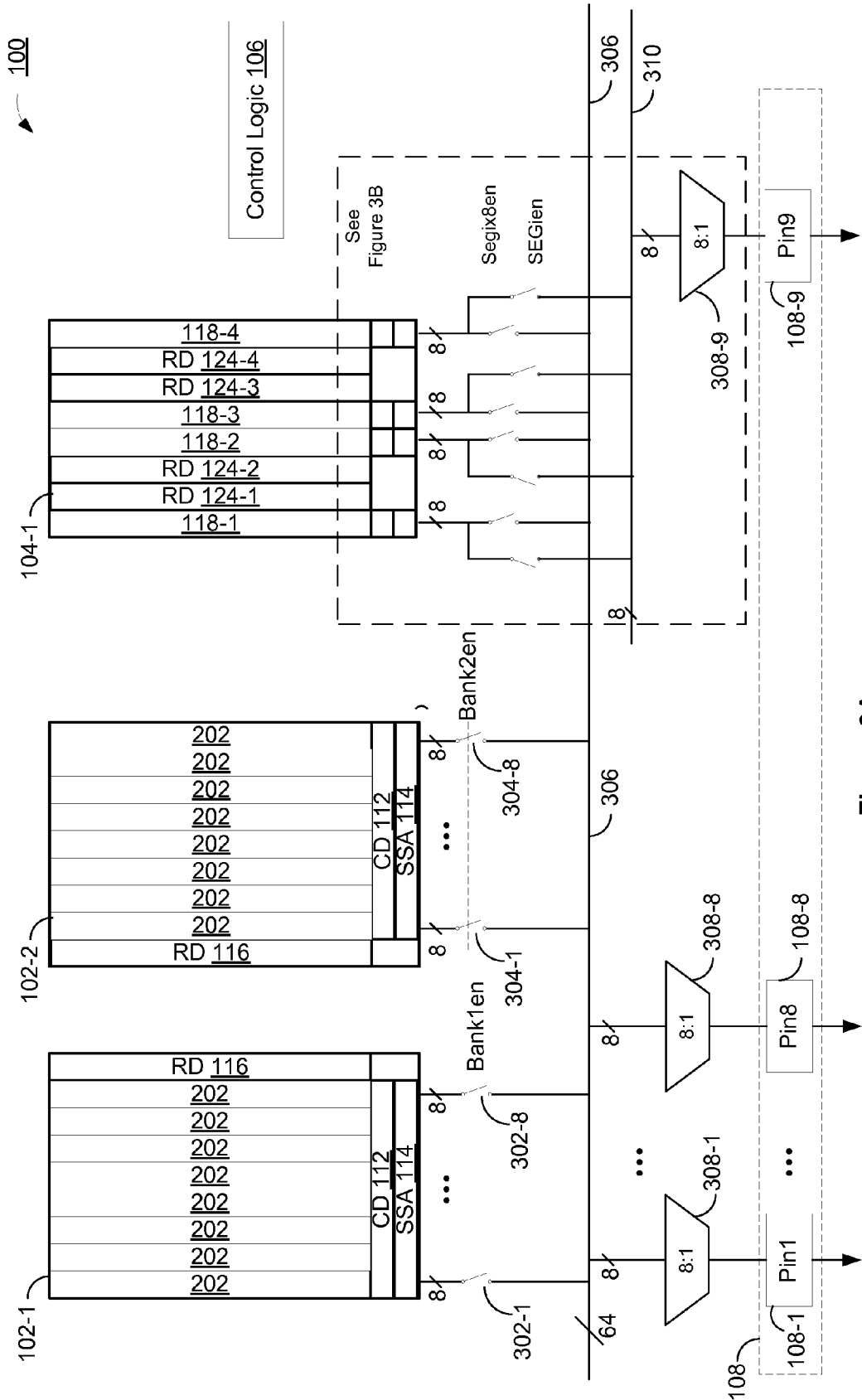


Figure 3A

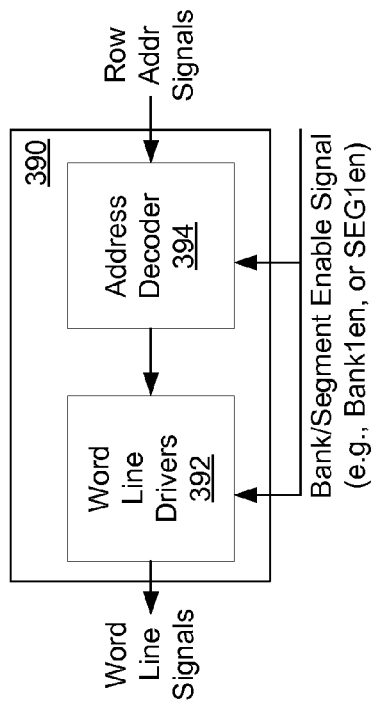


Figure 3C

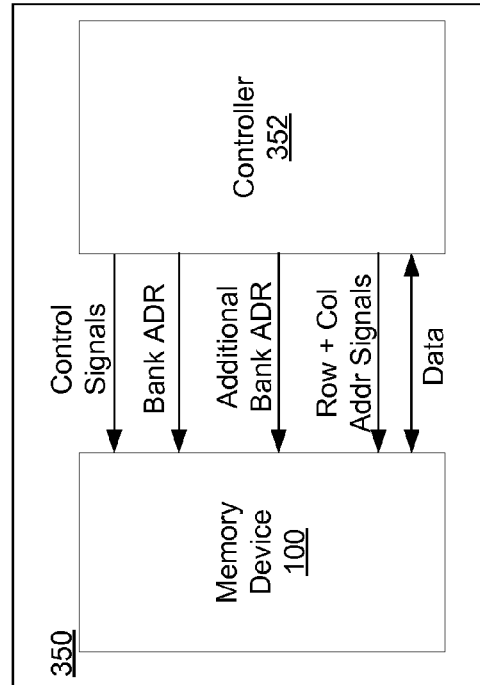


Figure 3D

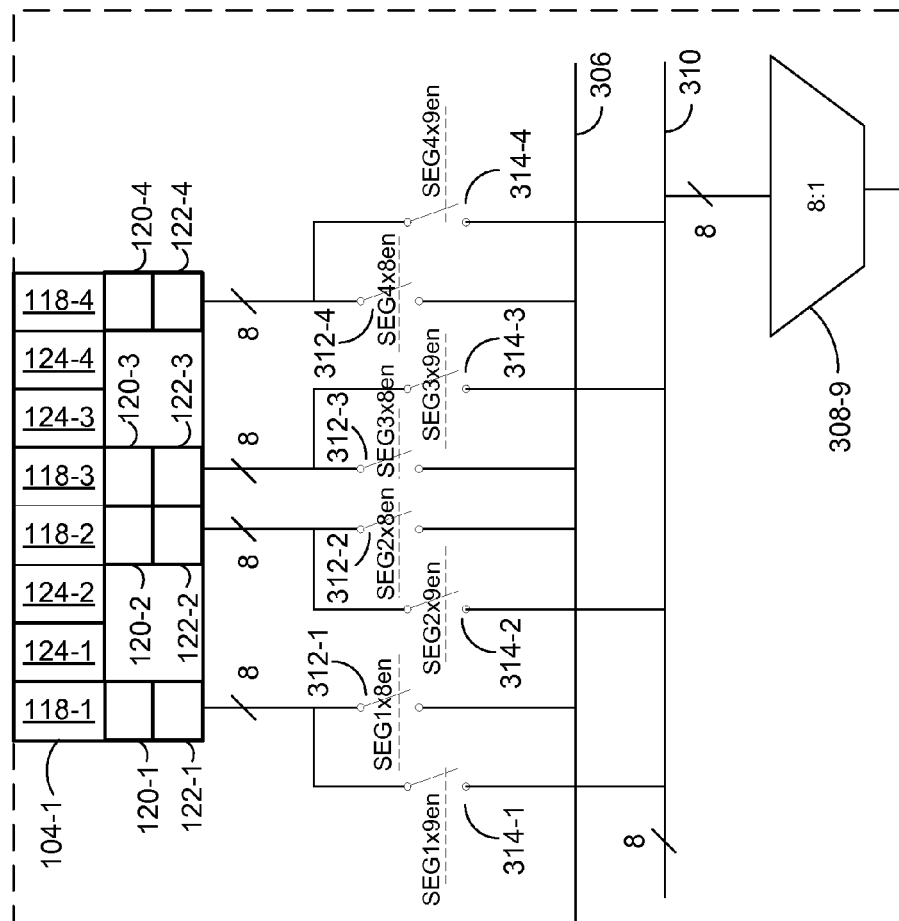


Figure 3B

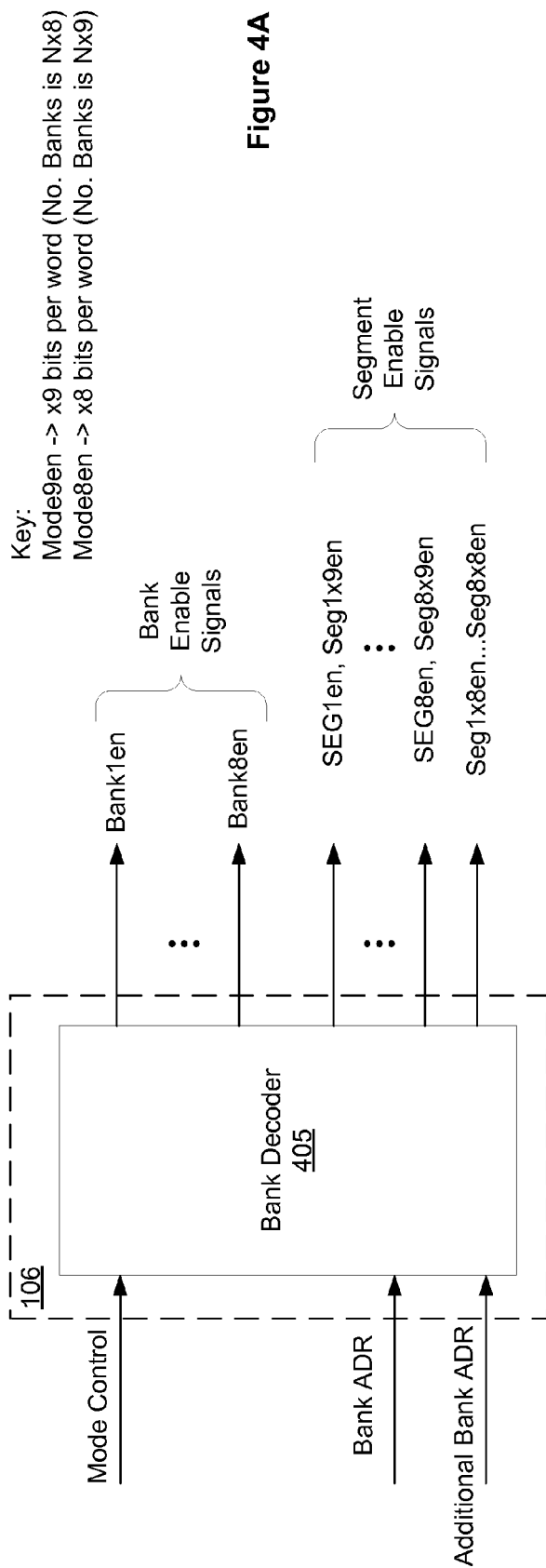


Figure 4A

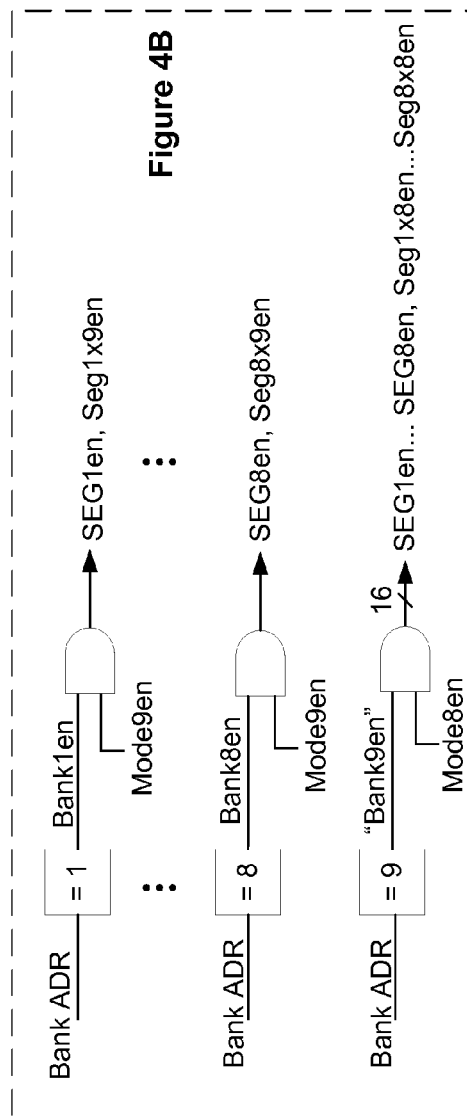


Figure 4B

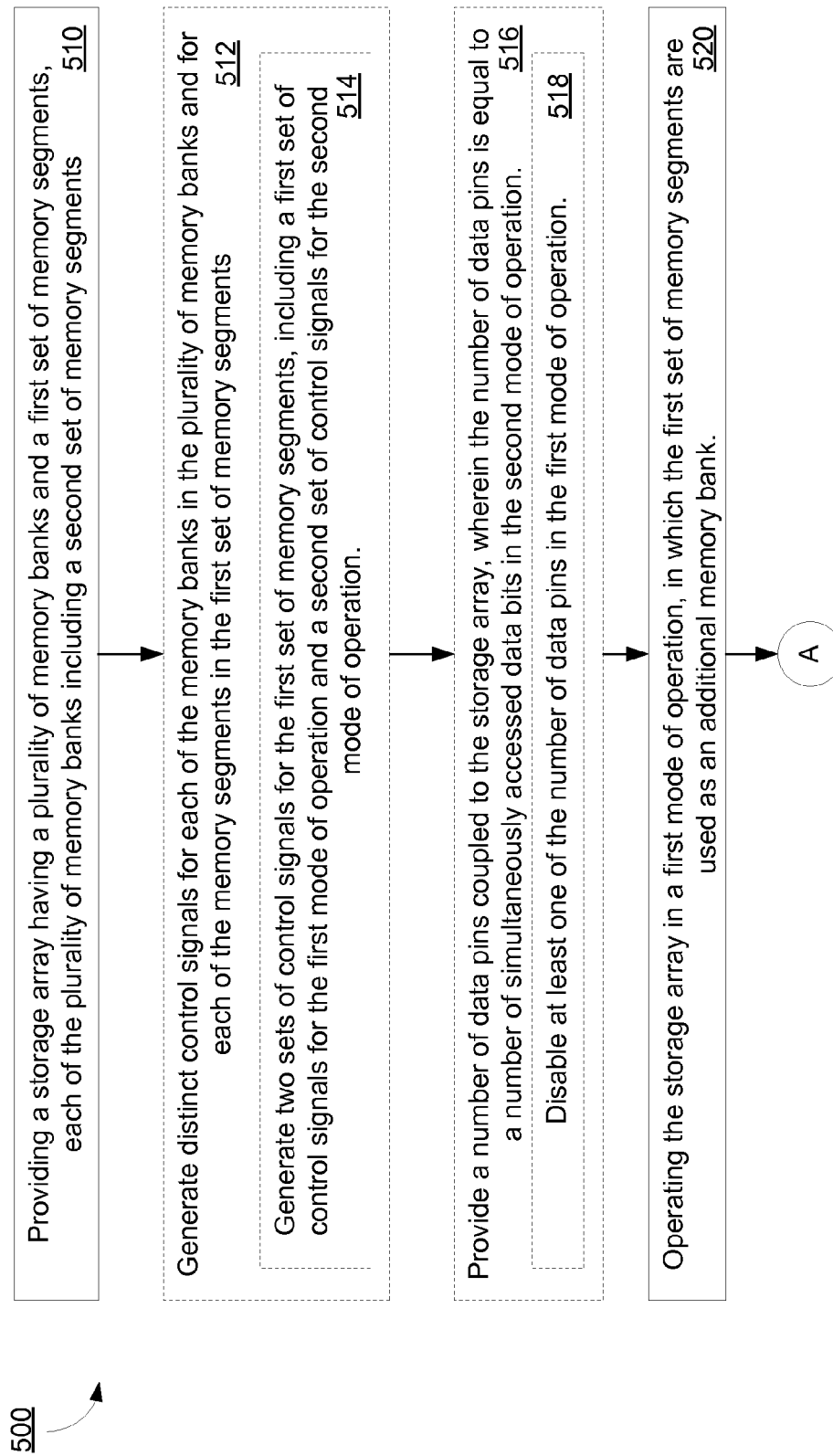


Figure 5A

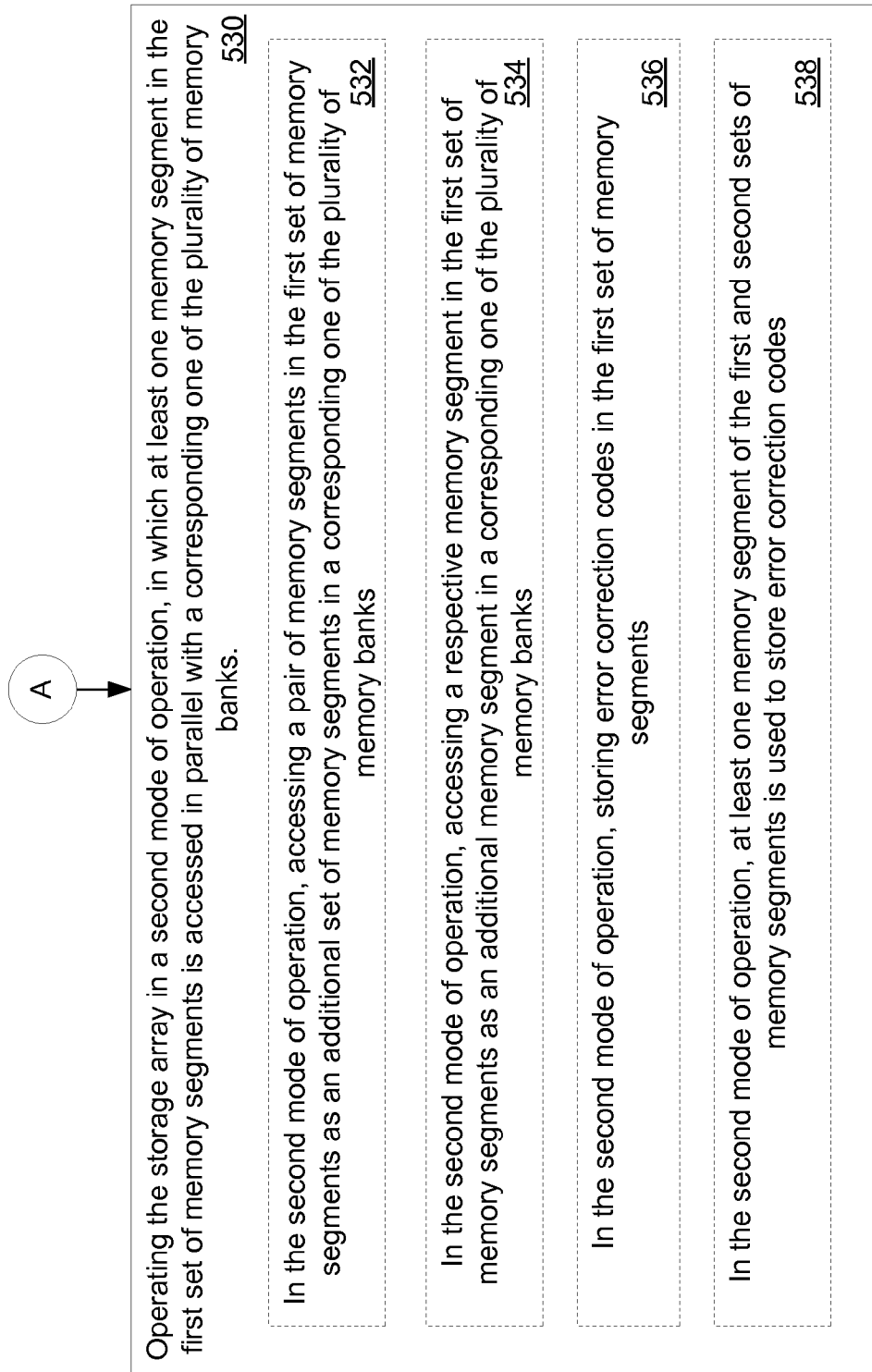


Figure 5B

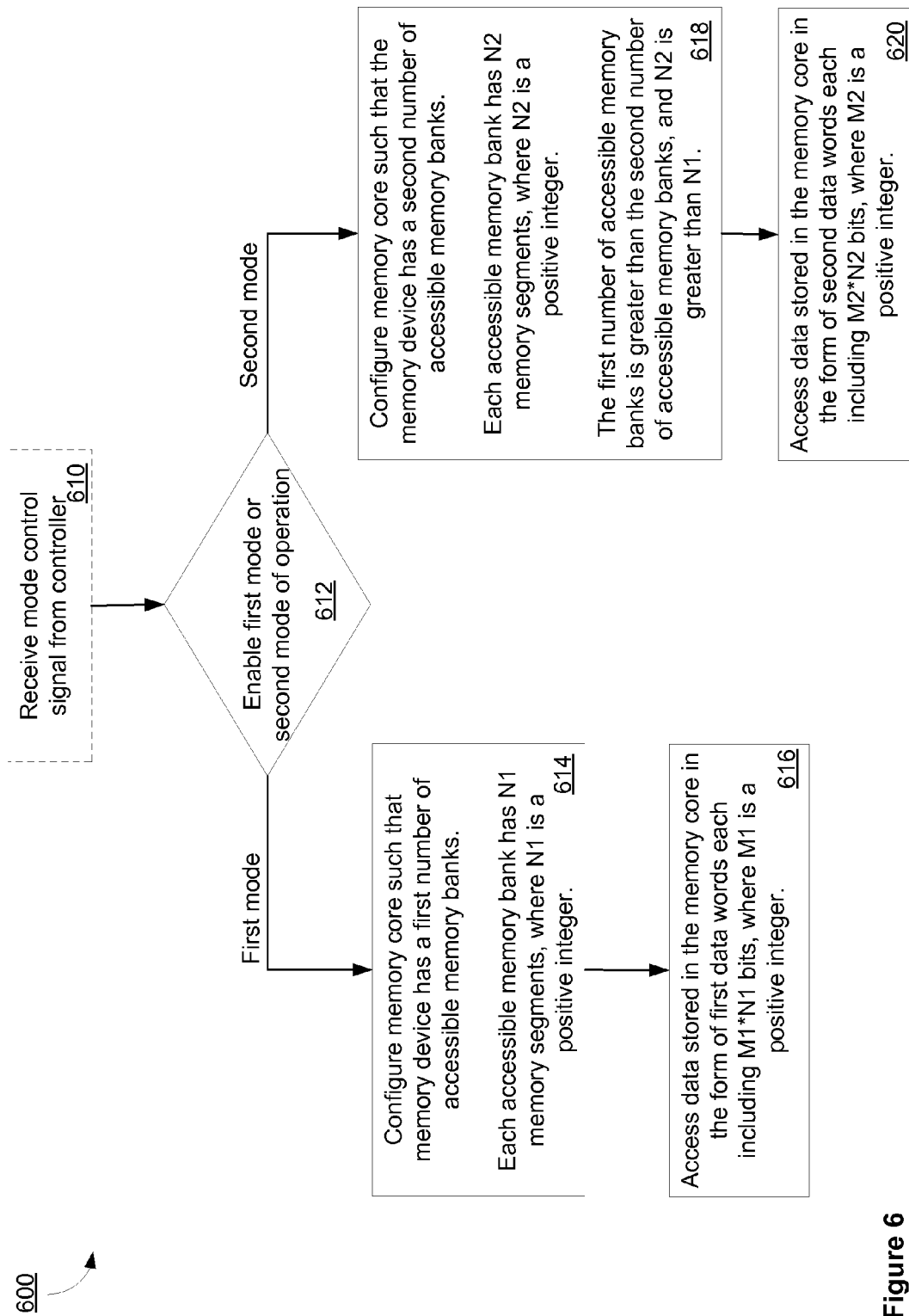


Figure 6

CONFIGURABLE MEMORY BANKS OF A MEMORY DEVICE

CROSS REFERENCE TO RELATED APPLICATIONS

This Application is a United States National Stage Application filed under 35 U.S.C. §371 of PCT Patent Application Serial No. PCT/US2010/046269 filed on Aug. 23, 2010, which claims the benefit of and priority to U.S. Provisional Patent Application Ser. No. 61/243,114 filed on Sep. 16, 2009, both of which are hereby incorporated by reference in their entireties.

TECHNICAL FIELD

The subject matter disclosed herein relates generally to memory systems having memory modules. More specifically, the subject matter relates high-speed memory modules with configurable banks.

BACKGROUND

The main operating memory of virtually all modern desktop and laptop computers is implemented using dynamic random access memory (DRAM) components. DRAM is relatively inexpensive and provides excellent storage density relative to other types of semiconductor memory. The internal column and data path structure of a DRAM, however, puts severe restrictions on the granularity of data access, making flexible memory systems difficult to design.

BRIEF DESCRIPTION OF THE DRAWINGS

FIG. 1 is a block diagram illustrating a portion of a memory device in accordance with some embodiments.

FIG. 2A is a block diagram of a memory device in $\times 8$ mode in accordance with some embodiments.

FIG. 2B is a block diagram of a memory device in $\times 9$ mode in accordance with some embodiments.

FIGS. 3A-B are schematic diagrams of portions of a memory device in accordance with some embodiments.

FIG. 3C is block diagram illustrating a row decoder in accordance with some embodiments.

FIG. 3D is a block diagram illustrating a memory system in accordance with some embodiments.

FIGS. 4A-B are block diagrams of logic for generating control signals in accordance with some embodiments.

FIGS. 5A-5B are a flow diagram of a method of operating a memory module in accordance with some embodiments.

FIG. 6 is a flow diagram of a method of operating a memory device in accordance with some embodiments.

Like reference numerals refer to corresponding parts throughout the drawings.

DESCRIPTION OF EMBODIMENTS

A memory device has a storage array having a plurality of accessible memory banks and, in addition, a configurable first set of memory segments. The plurality of accessible memory banks include a second set of memory segments. During a first mode of operation, the first set of memory segments is configured to be an additional accessible memory bank. During a second mode of operation, at least one memory segment in the first set of memory segments is configured to be accessed in parallel with a corresponding one of the plurality of accessible memory banks.

In some embodiments, during the second mode of operation, each memory segment in the first set of memory segments is configured to be an additional segment of a corresponding one of the plurality of memory banks.

In some embodiments, each memory segment in the first set of memory segments is coupled to a distinct word line driver. In some embodiments, each memory segment in the first set of memory segments has its own row decoder, each of which includes a respective word line driver. In other embodiments, the first set of memory segments includes a plurality of memory segment pairs and each respective memory segment pair in the first set of memory segments is coupled to a respective word line driver.

In some embodiments, the first set of memory segments are used to store error correction or error detection codes during the second mode of operation. Alternately, in some embodiments, at least one memory segment of the first and second sets of memory segments is used to error correction or error detection codes during the second mode of operation.

In some embodiments, the memory device includes mode control circuitry coupled to the storage array to generate distinct control signals for each of the memory banks in the plurality of accessible memory banks and for each of the memory segments in the first set of memory segments. In some embodiments, the mode control circuitry is configured to generate two sets of control signals for the first set of memory segments, including a first set of control signals for the first mode of operation and a second set of control signals for the second mode of operation.

In some embodiments, the memory device includes a number of data pins that are coupled to the storage array, wherein the number of data pins is equal to a number of simultaneously accessed data bits in the second mode of operation. In some embodiments, at least one of the number of data pins is disabled in the first mode of operation.

A memory device has a first number of accessible memory banks in a first mode of operation and a second number of accessible memory banks in a second mode of operation. During the first mode of operation, each of the first number of accessible memory banks is comprised of a first number of memory segments and during the second mode of operation, each of the second number of accessible memory banks is comprised of a second number of memory segments. The first number of accessible memory banks is greater than the second number of accessible memory banks, and the second number of memory segments is greater than the first number of memory segments.

In some embodiments, the memory device includes mode control circuitry that is coupled to the storage array to generate distinct control signals for the first mode of operation and the second mode of operation.

In some embodiments, the memory device also includes a number of data pins that are coupled to the storage array, wherein the number of data pins is equal to a number of simultaneously accessed data bits in the second mode of operation. In some embodiments, at least one of the number of data pins is disabled in the first mode of operation.

In some embodiments, at least one memory segment in each of the second number of accessible memory banks is used to store error correction or error detection codes in the second mode of operation.

A method of operating a memory module includes providing a storage array having a plurality of memory banks and a first set of memory segments, using the first set of memory segments as an additional memory bank in a first mode of operation, and accessing a memory segment in the first set of memory segments in parallel with a corresponding one of the

3

plurality of memory banks in a second mode of operation. Each of the plurality of memory banks includes a second set of memory segments.

In some embodiments, the method further includes accessing a pair of memory segments in the first set of memory segments as an additional set of memory segments in a corresponding one of the plurality of memory banks in the second mode of operation. Alternately, the method further includes accessing a respective memory segment in the first set of memory segments as an additional memory segment in a corresponding one of the plurality of memory banks in the second mode of operation.

In some embodiments, the method further includes generating distinct control signals for each of the memory banks in the plurality of memory banks and for each of the memory segments in the first set of memory segments. In some embodiments, the method further includes generating two sets of control signals for the first set of memory segments, including a first set of control signals for the first mode of operation and a second set of control signals for the second mode of operation.

In some embodiments, the method further includes providing a number of data pins coupled to the storage array, wherein the number of data pins is equal to a number of simultaneously accessed data bits in the second mode of operation. In some embodiments, the method includes disabling at least one of the number of data pins in the first mode of operation.

In some embodiments, the method includes storing error correction or error detection codes in the first set of memory segments in the second mode of operation. Alternately, the method includes storing error correction or error detection codes in one of the first and second sets of memory segments in the second mode of operation.

A method of operating a memory device having a memory core includes, in a first mode of operation, configuring the memory core such that the memory device is comprised of a first number of accessible memory banks and that each of the first number of accessible memory banks is comprised of $N1$ memory segments, where $N1$ is a positive integer, and accessing data stored in the memory core in the form of first data words each including $M1*N1$ bits, where $M1$ is a positive integer. The method also includes, in a second mode of operation, configuring the memory core such that the memory device is comprised of a second number of accessible memory banks and that each of the second number of accessible memory banks is comprised of $N2$ memory segments, where $N2$ is a positive integer, and accessing data stored in the memory core in the form of first data words each including $M2*N2$ bits, where $M2$ is a positive integer. The first number of accessible memory banks is greater than the second number of accessible memory banks, and $N2$ is greater than $N1$. In some embodiments, a mode control signal is received from a controller, where the mode control signal is used to enable one of the first mode of operation or the second mode of operation.

Reference will now be made in detail to embodiments, examples of which are illustrated in the accompanying drawings. In the following detailed description, numerous specific details are set forth in order to provide a thorough understanding of the present invention. It will be apparent, to one of ordinary skill in the art, however, that the present invention may be practiced without these specific details. In other instances, well-known methods, procedures, components, and circuits have not been described in detail so as not to unnecessarily obscure aspects of the embodiments.

4

FIG. 1 is a block diagram illustrating a memory device **100** in accordance with some embodiments. In some embodiments, the memory device is a dynamic random access memory (DRAM) component. The memory device **100** can be part of a larger electronic system. In some embodiments, memory device **100** is coupled to a microprocessor and provides data retrieved from the plurality of memory banks **102** and the plurality of supplementary segments **104** to the microprocessor via pins **108**.

The memory device **100** supports two modes of operation. In a first mode of operation, data can be accessed as a multiple of 8 bits per word, and in a second mode of operation, data is accessed as a multiple of 9 bits per word. The first mode of operation is referred to herein as the “ $\times 8$ mode” and the second mode of operation is referred to herein as the “ $\times 9$ mode.” In the $\times 8$ mode, the memory device **100** is configured to have a multiple of 9 memory banks (i.e., the number of memory banks is equal to $M \times 9$, where M is an integer greater than 0). In the $\times 9$ mode, the memory device **100** is configured to have a multiple of 8 memory banks (i.e., the number of memory banks is equal to $N \times 8$, where N is an integer greater than 0). In the following description, memory device **100** is referred to as being able to access data comprised of both 8 and 9 bits per word. One skilled in the art will recognize, however, that a memory device as described herein would be suitable to access data comprised of any multiple of 8 and 9 bits per word by merely multiplying the described components, or by increasing the data width of the described components.

As shown in FIG. 1, the memory device **100** includes a plurality of memory banks **102-1**, **102-2**, . . . **102-8**, a set of supplementary segments including a plurality of supplementary segments **104-1** and a plurality of supplementary segments **104-2**, control logic **106**, and pins **108**. In some embodiments, memory device **100** may also include other components not shown in FIG. 1. As detailed in FIG. 3A, pins **108** are comprised of a plurality of data pins **108-1** . . . **108-9** (FIG. 3A). As discussed further below in relation to FIGS. 4A and 4B, various control signals (e.g., bank enable signals and segment pair enable signals) are generated by control logic **106**.

Each of the plurality of memory banks **102-1** . . . **102-8** include at least a memory array/core **110**, column decoder (CD) **112**, secondary sense amplifiers (SSA) **114**, and row decoder (RD) **116**. Each of the plurality of memory banks **102-1** . . . **102-8** receives a plurality of control signal (e.g., Bank1en . . . Bank8en) from control logic **106** that enables its operation. Column decoder CD **112** and row decoder RD **116** receive and decode address signals when enabled by a bank enable signal received from control logic **106**. The address signals and bank enable signal together identify which bank should be enabled and which row/column of the enabled bank to access. As discussed further below in relation to FIG. 3C, each row decoder RD **116** uses address signals and a respective control signal (i.e., bank enable signal) to generate word line signals. Secondary sense amplifiers SSA **114** sense data located in the accessed locations of the enabled bank and send the sensed data to pins **108** in a read operation. In a write operation, write circuitry (not shown) parallel to secondary sense amplifiers SSA **114** sends data from the pins **108** to the memory array **110**. In some embodiments, additional circuitry processes the data between the memory array **110** and the pins **108** in both read and write operations.

The plurality of supplementary segments **104-1** and supplementary segments **104-2** each include a plurality of memory arrays/cores **118-1** . . . **118-4** and **118-5** . . . **118-8**, respectively, a plurality of column decoders CD **120-1** . . .

120-4 and CD 120-5 . . . 120-8, respectively, a plurality of supplemental sense amplifiers SSA 122-1 . . . 122-4 and SSA 122-5 . . . 122-8, respectively, and a plurality of RD 124-1 . . . 124-4 and 124-5 . . . 124-8, respectively. Each of these components is similar to the corresponding component of each of the plurality of memory banks 102-1 . . . 102-8. For example, the plurality of row decoders RD 124-1 . . . 124-4 and RD 124-5 . . . 124-8 are similar to row decoder RD 116. In some embodiments, each of the plurality of memory arrays/cores 118-1 . . . 118-8 has its own row decoder. In other embodiments, a row decoder is shared by one or more of the plurality of memory arrays/cores 118-1 . . . 118-8. The plurality of supplementary segments 104-1 and supplementary segments 104-2 each receive a plurality of control signals (e.g., SEG1en . . . SEG4en and SEG5en . . . SEG8en, respectively, and SEG1x8en . . . Seg4x8en and Seg5x8en and Seg8x8en, respectively) from control logic 106.

In the x8 mode, the supplementary segments 104-1 and supplementary segments 104-2 are configured to be a ninth memory bank. The x8 mode configuration is described in more detail in connection with FIG. 2A. As shown in FIG. 2A, memory device 100x8 includes a plurality of memory banks A1 . . . A9. Memory banks A1 . . . A8 are memory banks 102-1 . . . 102-8 (FIG. 1), and as such, memory banks A1 . . . A8 each include a column decoder CD 112 and row decoder RD 116. Each memory bank A1 . . . A8 also includes a plurality of memory segments 202, which are components of the memory bank's memory array/core 110 (FIG. 1). As stated above, in the x8 mode, the supplementary segments 104-1 and supplementary segments 104-2 are configured to be a ninth memory bank (i.e., memory bank A9). Memory bank A9 includes a plurality of memory segments 204-1 . . . 204-8 (corresponding to memory arrays/cores 118-1 . . . 118-8 in FIG. 1), the plurality of row decoders RD 124-1 . . . 124-8, and the plurality of column decoders CD 120-1 . . . 120-8. As described in further detail below in connection with FIGS. 3A and 3B, when one of the plurality of memory banks A1 . . . A8 or memory bank A9 is enabled in x8 mode, the memory segments in the enabled memory bank are accessed simultaneously and the accessed data is sent to (or received from) pins 108 (FIG. 1).

Returning to FIG. 1, in the x9 mode, at least one of the plurality of memory arrays/cores 118-1 . . . 118-8 in supplementary segments 104-1 and supplementary segments 104-2 is configured to be accessed in parallel with a corresponding one of the memory banks 102-1 . . . 102-8. The x9 mode configuration is described in more detail in connection with FIG. 2B.

As shown in FIG. 2B, memory device 100x9 includes a plurality of memory banks B1 . . . B8. Memory banks B1 . . . B8 are memory banks 102-1 . . . 102-8 (FIG. 1), and as such, memory banks B1 . . . B8 each include a column decoder CD 112 and row decoder RD 116. Each memory bank B1 . . . B8 also includes a plurality of memory segments 202, which are components of the memory bank's memory array/core 110 (FIG. 1). Memory device 100x9 further includes a plurality of memory segments 204-1 . . . 204-8 (i.e., the plurality of memory arrays/cores 118-1 . . . 118-8), each of which has a corresponding column decoder CD 120 (not shown in FIG. 2B) and row decoder RD 124-1 . . . 124-8. When one of the memory banks B1 . . . B8 is enabled, a corresponding one of the memory segments 204-1 . . . 204-8 is accessed in parallel with the enabled bank. Accordingly, the accessed memory segment acts as a supplementary memory segment for the enabled memory bank. For example, in some embodiments, when memory bank B1 is enabled, memory segment 204-1 is also accessed. Additionally, in some embodiments, when

memory bank B5 is enabled, memory segment 204-5 is also accessed. As described below in connection with FIGS. 3A and 3B, when one of the plurality of memory banks B1 . . . B8 is accessed in x9 mode, one of the plurality of memory segments 204-1 . . . 204-8 is also accessed, and the accessed data from both the accessed memory bank and the accessed memory segment is sent to pins 108 (FIG. 1). Stated another way, in x9 mode, each bank includes both a main set of memory segments 202 and at least one supplementary memory segment 204.

In some embodiments, when the memory device 100 is operated in x9 mode, the supplementary memory segments 204 (memory arrays/cores 118-1 . . . 118-8) store error correction or error detection codes. Specifically, the plurality of memory arrays/cores 118-1 . . . 118-8 store parity bits or error correction or error detection codes. In other embodiments, when the memory device 100 is operated in x9 mode, at least one memory segment 202 or memory segment 204 of each memory bank is used to store error correction or error detection codes. In the latter embodiments, the error correction or error detection codes need not be stored in the supplementary memory segments 204, and

FIGS. 3A and 3B illustrate a portion of the memory device 100 in accordance with some embodiments. As shown in FIG. 3A, memory banks 102-1 and 102-2 are coupled to bus 306 via switches 302-1 . . . 302-8 and 304-1 . . . 304-8, respectively. Switches 302-1 . . . 302-8 are controlled by bank control signal Bank1en and switches 304-1 . . . 304-8 are controlled by bank control signal Bank2en. As described further below in connection with FIGS. 4A and 4B, control logic 106 generates a plurality of bank control signals, including Bank1en and Bank2en. While only two memory banks (i.e., memory banks 102-1 and 102-2) are shown in FIG. 3A, each of the remaining memory banks of the plurality of memory banks (i.e., memory banks 102-3 . . . 102-8) is also coupled to bus 306 via a similar set of switches controlled by a bank control signal received from control logic 106.

Pins 108 include a plurality of data pins 108-1 . . . 108-9. Eight of the data pins 108-1 . . . 108-8 are coupled to bus 306 via a corresponding plurality of multiplexors 308-1 . . . 308-9. The ninth data pin 108-9 is coupled to bus 310 by a multiplexor 308-9. In some embodiments, data pin 108-9 is disabled in x8 mode (e.g., by tri-stating the inputs to multiplexor 308-9, or by disabling multiplexor 308-9 with the a mode signal).

FIG. 3B illustrates in detail how supplementary segment 104-1 is coupled to bus 306 (for conveying data to and from the first eight pins 108-1 to 108-8) and bus 310 (for conveying data to and from the ninth pin 108-9) in accordance with some embodiments. As also shown in FIG. 3B, supplementary segment 104-1 includes a plurality of memory segments 118-1 . . . 118-4, a plurality of row decoders 124-1 . . . 124-4, a plurality of column decoders 120-1 . . . 120-4, and a plurality of secondary sense amplifiers 122-1 . . . 122-4. Supplementary segment 104-1 is coupled to a plurality of switches 312-1 . . . 312-4 and 314-1 . . . 314-4. More specifically, in this example supplementary segment 104-1 is coupled to two sets of switches, one (312-1 . . . 312-4) for coupling the supplementary segment 104-1 to bus 306, and the other (314-1 . . . 314-4) for coupling the supplementary segment 104-1 to bus 310.

A first set of switches 312-1 . . . 312-4 couple supplementary segment 104-1 to bus 306 (which is coupled to the first eight pins, 108-1 . . . 108-8) and are controlled by Seg1x8en . . . Seg4x8en. In this example, each switch 312 couples eight parallel data lines (carrying data to or from the memory array 118 in a respective memory segment 204) of

the supplementary segment **104-1** to the bus **306**. Because supplementary segment **104-2** (FIG. 1) is essentially a mirror image of supplementary segment **104-1**, supplementary segment **104-2** (FIG. 1) is coupled to bus **306** via a plurality of switches **312-5** . . . **312-8** (not shown) that are controlled by Seg5×8en . . . Seg8×8en (FIG. 1), respectively. When the memory device **100** (FIG. 1) is operating in the ×8 mode and Bank **9** (i.e., memory bank A9) is enabled, the plurality of switches **312-1** . . . **312-4** and **312-5** . . . **312-8** (not shown) are also enabled. As such, each of the plurality of memory segments **118-1** . . . **118-8** is accessed when Bank **9** is enabled.

A second set of switches **314-1** . . . **314-4** couple supplementary segment **104-1** to bus **310** (which is coupled to the ninth pin, **108-9**). Switch **314-1** is controlled by SEG1×9en, switch **314-2** is controlled by SEG2×9en, switch **314-3** is controlled by SEG3×9en, and switch **314-4** is controlled by SEG4×9en. In this example, each switch **314** couples eight parallel data lines (carrying data to or from the memory array **118** in a respective memory segment **204**) of the supplementary segment **104-1** to the bus **310**. Because supplementary segment **104-2** (FIG. 1) is essentially a mirror image of supplementary segment **104-1**, supplementary segment **104-2** (FIG. 1) is coupled to bus **310** via a plurality of switches **314-5** . . . **314-8** (not shown) that are controlled by Seg5×9en . . . Seg8×9en (FIG. 1), respectively. When the memory device **100** (FIG. 1) is operating in the ×9 mode, only one of switches **314-1** . . . **314-8** is enabled, and thus, only the corresponding memory segment of the plurality of memory segments **204-1** . . . **204-8** (is accessed).

Seg1×8en . . . Seg8×8en and SEG1en . . . SEG8en are generated by control logic **106** (FIG. 3A) as described below in connection with FIGS. 4A and 4B.

The operation of memory banks **102-1** . . . **102-8** is the same irrespective of what mode the memory device **100** is operating in. In ×8 mode, only one of the plurality of memory banks A1 . . . A9 (FIG. 2A) is enabled at any one time. In ×9 mode, one of the plurality of memory banks B1 . . . B8 (FIG. 2B) and one of the plurality of memory segments **204-1** . . . **204-8** are enabled at the same time.

For example, in ×8 mode, only switches **302-1** . . . **302-8** are engaged when memory bank A1 (i.e., memory bank **102-1**) is enabled. The 8 bits of data recovered from memory bank **102-1** are sent to bus **306** and then to the corresponding data pins **108-1** . . . **108-8**. Also for example, in ×8 mode, when memory bank A9 (i.e., supplementary segments **104-1** and supplementary segments **104-2**) is enabled, switches **312-1** . . . **312-8** are enabled. Accordingly, all of the memory arrays/cores **118-1** . . . **118-8** (in memory segments **204-1** . . . **204-9**) are accessed when memory bank A9 is accessed in the ×8 mode.

Also for example, in ×9 mode, switches **302-1** . . . **302-8** and switch **314-1** are engaged when memory bank B1 (i.e., memory bank **102-1**) and memory array/core **118-1** (in memory segment **204-1**) are enabled. Again, the 8 bits of data recovered from memory bank **102-1** are sent to bus **306** and then to the corresponding data pins **108-1** . . . **108-8**. The additional data recovered from memory segment **204-1** (memory array/core **118-1**) is sent to bus **310** and then to pin **9**.

FIG. 3C illustrates a row decoder RD **390** in accordance with some embodiments. RD **390** may be RD **116** (i.e., one of the memory bank row decoders) or one of the plurality of row decoders **124-1** . . . **124-8** (i.e., one of the segment row decoders). Row decoder RD **390** includes an address decoder **394** and word line drivers **392**. Row decoder RD **390** generates word line signals by decoding a set of address signals (sometimes called the row address bits (Row Addr Signals))

when a corresponding bank enable signal (e.g., Bank1en) or segment enable signal (e.g., SEG1en) is active. The word line signals indicate the word line in the memory array/core (e.g., memory array/core **110**) to be accessed. In some embodiments, each of the plurality of memory segments **118-1** . . . **118-8** have a dedicated word line driver **392**. In other embodiments, a pair of the plurality of memory segments **118-1** . . . **118-8** share a word line driver **392**.

FIG. 3D illustrates a memory system **350** in accordance with some embodiments. As shown in FIG. 3D, the memory system includes memory device **100** and controller **352** (e.g., a memory controller or other system controller). The memory device **100** can be any of the memory devices shown in FIGS. 1, 2A-2B, and can incorporate the circuitry shown in FIGS. 3A-3C and the decoder circuitry of FIGS. 4A-4B. The memory device **100** and controller **352** are interconnected by control, address and data signal lines (sometimes called buses, or wired signal lines, or traces if on a printed circuit board, etc.) Memory device **100** receives a one or more control signals (e.g., a mode control signal, labeled Mode Control in other Figures), a bank address signal (Bank ADR), an additional bank address signal (Additional Bank ADR), and row and column address bits (Row+Col Addr Signals) from controller **352**. Data signals are conveyed to the memory device **100** from the controller **352** when writing data to the memory device **100**, and from the memory device **100** to the controller **352** when reading data from the memory device **100**. As discussed further below in relation to FIGS. 4A and 4B, the mode control signal (Mode Control), the bank address signal (Bank ADR), and the additional bank address signal (Additional Bank ADR) are used by control logic **106** (FIG. 4A) to generate various control signals (e.g., bank enable signals and segment pair enable signals). As discussed above in relation to FIG. 3C, row decoder **390** uses row address bits (Row Addr Signals) to generate word line signals.

FIGS. 4A and 4B illustrate control logic **106** in accordance with some embodiments. As shown in FIG. 4A, control logic **106** generates the plurality of control signals used by the memory device **100** (FIG. 1). Control logic **106** comprises a bank decoder **405**, which receives a mode control signal (Mode Control), a bank address signal (Bank ADR), and an additional bank address signal (Additional Bank ADR). As stated above in relation to FIG. 3D, the mode control signal (Mode Control), bank address signal (Bank ADR), and additional bank address signal (Additional Bank ADR) are received from controller **352** in some embodiments. Mode Control indicates what mode the memory device **100** (FIG. 1) is operating in. When the memory device **100** (FIG. 1) is operating in the ×8 mode, Mode Control is equal to Mode8en. When the memory device **100** (FIG. 1) is operating in the ×9 mode, Mode Control is equal to Mode9en. Bank ADR indicates what memory bank of the plurality of memory banks **102-1** . . . **102-8** (FIG. 1) should be accessed. Bank ADR is typically a multi-bit value, for example, a three, four or five bit value. Additional Bank ADR indicates what particular segment/word line of the accessed memory bank should be accessed. Additional Bank ADR is typically a single bit value (e.g., equal to 0 or 1).

Bank decoder **405** generates a plurality of bank enable signals Bank1en . . . Bank8en, which are used to enable the plurality of memory banks as described above in connection with FIG. 3A. Bank decoder **405** also generates a plurality of segment pair enable signals SEG1en, Seg1×9en . . . SEG8en, Seg8×9en and Seg1×8en . . . Seg8×8en. The bank enable signals and segment enable signals are used by the plurality of control switches **302-1** . . . **302-8** (FIG. 3A) and the plurality

of row decoders RD 116 and 124-1 . . . 124-8 (FIG. 1) to access data stored in the plurality of memory banks 102-1 . . . 102-8 (FIG. 1).

As shown in FIG. 4B, when Bank ADR is equal to 1, Bank1en and SEG1en are generated. Similarly, Bank8en and SEG8en are generated when Bank ADR is equal to 8. When Mode Control is equal to Mode9en, Segix9en is also generated, where i identifies (or is equal to) the bank enabled. For example, Segix9en is Seg1x9en when Bank ADR is equal to 1 and Segix9en is Seg8x9en when Bank ADR is equal to 8.

Additionally as shown in FIG. 4B, SEG1en . . . SEG8en and Seg1x8en . . . Seg8x8en are generated when Bank ADR is equal to 9 (and thus, "Bank9en" is generated) and Mode Control is equal to Mode8en. SEG1en . . . SEG8en and Seg1x8en . . . Seg8x8en are used to access specific segments of memory bank A9 (FIG. 2A). It is noted that the SEG1en . . . SEG8en (SEGien) signals are each produced by two circuits, one for the x8 mode and one for the x9, and thus, in effect, each of the SEG1en . . . SEG8en signals is produced by a logical OR of the outputs from those two circuits—when either circuit produces an active SEGien signal, the SEGien signal is active.

FIGS. 5A-5B are a flow diagram illustrating a process 500 of operating a memory module in accordance with some embodiments. Process 500 can be performed using the memory device 100 described above with reference to FIGS. 1-4B. As shown in FIGS. 5A-5B, the process 500 includes providing a storage array having a plurality of memory banks (e.g., memory banks 102-1 . . . 102-8 (FIG. 1)) and a first set of memory segments (e.g., supplementary segments 104-1 and supplementary segments 104-2 (FIG. 1)), where each of the plurality of memory banks includes a second set of memory segments (e.g., memory segments 202 (FIG. 2A)) (510). The process 500 further includes operating the storage array in a first mode of operation, in which the first set of memory segments are used as an additional memory bank (520). The storage array is also operated in a second mode of operation, in which at least one memory segment in the first set of memory segments is accessed in parallel with a corresponding one of the plurality of memory banks (530).

In some embodiments, the method includes generating distinct control signals for each of the memory banks in the plurality of memory banks and for each of the memory segments in the first set of memory segments (512). For example, this may include generating two sets of control signals for the first set of memory segments, including a first set of control signals for the first mode of operation and a second set of control signals for the second mode of operation (514).

In some embodiments, the method includes providing a number of data pins coupled to the storage array, wherein the number of data pins is equal to a number of simultaneously accessed data bits in the second mode of operation (516). In addition, the method may optionally include disabling at least one of the number of data pins in the first mode of operation (518).

In some embodiments, the method includes, in the second mode of operation, accessing a pair of memory segments in the first set of memory segments as an additional set of memory segments in a corresponding one of the plurality of memory banks (532). Alternately, the method includes, in the second mode of operation, accessing a respective memory segment in the first set of memory segments as an additional memory segment in a corresponding one of the plurality of memory banks (534).

In addition, in some embodiments the method includes, in the second mode of operation, storing error correction or error detection codes in the first set of memory segments (536).

Alternately, in the second mode of operation, at least one memory segment of the first and second sets of memory segments is used to store error correction or error detection codes (538).

FIG. 6 is a flow diagram illustrating a process 600 of operating a memory device having a memory core in accordance with some embodiments. Process 600 can be performed using the memory device 100 described above with reference to FIGS. 1-4B. As shown in FIG. 6, the process 600 includes two modes of operation (First mode and Second mode). In the first mode of operation, the process 600 includes configuring the memory device such that the memory device has a first number of accessible memory banks (e.g., memory banks A1 to A9 in FIG. 2A) (614). In some embodiments, the first number is a positive multiple of 9 (e.g., 9, 18, 36, etc.) Each accessible memory bank has N1 memory segments (e.g., regular segments 202 or supplementary segments 204 (FIG. 2A)), where N1 is a positive integer (e.g., a positive multiple of 8). The process 600 further includes accessing data stored in the memory core in the form of first data words each including M1*N1 bits, where M1 is a positive integer (e.g., 1, 2, 4, 8, etc.) (616). In a second mode of operation the process 600 includes configuring the memory core such that the memory device has a second number of accessible memory banks (e.g., memory banks B1 to B8 in FIG. 2B) (618). In some embodiments, the second number is a positive multiple of 8 (e.g., 8, 16, 32, etc.) Each accessible memory bank has N2 memory segments, where N2 is a positive integer (e.g., a positive multiple of 9). The first number of accessible memory banks is greater than the second number of accessible memory banks, and N2 is greater than N1. The process 600 further includes accessing data stored in the memory core in the form of second data words each including M2*N2 bits, where M2 is a positive integer (620). In some, but not necessarily all, embodiments, M1 and M2 are equal.

In some embodiments, the process 600 further includes receiving a mode control signal (e.g., a mode control signal (Mode Control) (FIG. 3D)) from a controller (e.g., controller 352 (FIG. 3D)) (610). The mode control signal is used to enable the first mode of operation or the second mode of operation (612) in the memory device.

The foregoing description, for purpose of explanation, has been described with reference to specific embodiments. However, the illustrative discussions above are not intended to be exhaustive or to limit the invention to the precise forms disclosed. Many modifications and variations are possible in view of the above teachings. The embodiments were chosen and described in order to best explain the principles of the invention and its practical applications, to thereby enable others skilled in the art to best utilize the invention and various embodiments with various modifications as are suited to the particular use contemplated.

What is claimed is:

1. A method of operating a memory module, comprising: providing a storage array having a plurality of memory banks and a first set of memory segments, wherein each of the plurality of memory banks includes a second set of memory segments;
 - in a first mode of operation, using the first set of memory segments as an additional memory bank; and
 - in a second mode of operation, accessing a memory segment in the first set of memory segments in parallel with a corresponding one of the plurality of memory banks; wherein in the first mode of operation, each accessible memory bank of the memory module has a first number of memory segments accessible in parallel, and in the

11

second mode of operation, each accessible memory bank of the memory module has a second number of memory segments accessible in parallel, wherein the second number is greater than the first number, and the first number of memory segments is an integer multiple of 8 and the second number of memory segments is an integer multiple of 9; and

wherein a total number of memory segments accessible in the first mode of operation is the same as a total number of memory segments accessible in the second mode of operation.

2. The method of claim 1, further comprising, in the second mode of operation, accessing a pair of memory segments in the first set of memory segments as an additional set of memory segments in a corresponding one of the plurality of memory banks.

3. The method of claim 1, further comprising, in the second mode of operation, accessing a respective memory segment in the first set of memory segments as an additional memory segment in a corresponding one of the plurality of memory banks.

4. The method of claim 1, further comprising generating distinct control signals for each of the memory banks in the plurality of memory banks and for each of the memory segments in the first set of memory segments.

5. The method of claim 4, further comprising generating two sets of control signals for the first set of memory segments, including a first set of control signals for the first mode of operation and a second set of control signals for the second mode of operation.

6. The method of claim 1, further comprising providing a number of data pins coupled to the storage array, wherein the number of data pins is equal to a number of simultaneously accessed data bits in the second mode of operation.

7. The method of claim 6, further comprising disabling at least one of the number of data pins in the first mode of operation.

8. The method of claim 1, further including, in the second mode of operation, storing error correction or error detection codes in the first set of memory segments.

9. The method of claim 1, further including, in the second mode of operation, at least one memory segment of the first and second sets of memory segments is used to store error correction or error detection codes.

10. A memory device, comprising:

a storage array having a first number of accessible memory banks in a first mode of operation and a second number of memory accessible memory banks in a second mode of operation;

wherein, in the first mode of operation, each of the first number of accessible memory banks is comprised of a first number of memory segments;

wherein, in the second mode of operation, each of the second number of accessible memory banks is comprised of a second number of memory segments, and the first number of memory segments is an integer multiple of 8 and the second number of memory segments is an integer multiple of 9;

wherein the first number of accessible memory banks is greater than the second number of accessible memory banks, and the second number of memory segments is greater than the first number of memory segments; and

wherein a total number of memory segments accessible in the first mode of operation is the same as a total number of memory segments accessible in the second mode of operation.

12

11. The memory device of claim 10, further comprising mode control circuitry coupled to the storage array to generate distinct control signals for the first mode of operation and the second mode of operation.

12. The memory device of claim 10, further comprising a number of data pins coupled to the storage array, wherein the number of data pins is equal to a number of simultaneously accessed data bits in the second mode of operation.

13. The memory device of claim 12, wherein at least one of the number of data pins is disabled in the first mode of operation.

14. The memory device of claim 10, wherein at least one memory segment in each of the second number of accessible memory banks is used to store error correction or error detection codes in the second mode of operation.

15. A method of operating a memory device having a memory core, comprising:

in a first mode of operation:

configuring the memory core such that the memory device is comprised of a first number of accessible memory banks and that each of the first number of accessible memory banks is comprised of $N1$ memory segments, where $N1$ is a positive integer, and accessing data stored in the memory core in the form of first data words each including $M1*N1$ bits, wherein $M1$ is a positive integer; and

in a second mode of operation:

configuring the memory core such that the memory device is comprised of a second number of accessible memory banks and that each of the second number of accessible memory banks is comprised of $N2$ memory segments, where $N2$ is a positive integer; and accessing data stored in the memory core in the form of second data words each including $M2*N2$ bits, wherein $M2$ is a positive integer;

wherein the first number of accessible memory banks is greater than the second number of accessible memory banks, $N2$ is greater than $N1$, and $N1$ is an integer multiple of 8 and $N2$ is an integer multiple of 9; and

wherein a total number of memory segments accessible in the first mode of operation is the same as a total number of memory segments accessible in the second mode of operation.

16. The method of claim 15, further comprising: receiving a mode control signal from a controller, wherein the mode control signal is used to enable one of the first mode of operation or the second mode of operation.

17. A memory device, comprising:

a storage array having a plurality of accessible memory banks and a configurable first set of memory segments, the plurality of accessible memory banks each including a respective second set of memory segments distinct from the configurable first set of memory segments; and wherein, in a first mode of operation, the configurable first set of memory segments is configured to be a single additional accessible memory bank;

wherein, in a second mode of operation, first, second, third and fourth memory segments in the configurable first set of memory segments are configured to be accessed in parallel with first, second, third and fourth memory banks of the plurality of accessible memory banks, respectively;

wherein, in the first mode of operation, each accessible memory bank of the memory device has a first number of memory segments accessible in parallel, and in the second mode of operation, each accessible memory bank of the memory device has a second number of memory

13

segments accessible in parallel, wherein the second number is greater than the first number; and wherein a total number of memory segments accessible in the first mode of operation is the same as a total number of memory segments accessible in the second mode of operation.

18. The memory device of claim 17, wherein, in the second mode of operation, each memory segment in the first set of memory segments is configured to be an additional segment of a corresponding one of the plurality of accessible memory banks.

19. The memory device of claim 17, wherein each memory segment in the first set of memory segments is coupled to a distinct word line driver.

20. The memory device of claim 17, wherein the first set of memory segments includes a plurality memory segment pairs, and wherein each respective memory segment pair in the first set of memory segments is coupled to a respective word line driver.

21. The memory device of claim 17, wherein the first set of memory segments are used to store error correction or error detection codes in the second mode of operation.

14

22. The memory device of claim 17, wherein at least one memory segment of the first and second sets of memory segments is used to store error correction or error detection codes in the second mode of operation.

23. The memory device of claim 17, further comprising mode control circuitry coupled to the storage array to generate distinct control signals for each of the memory banks in the plurality of accessible memory banks and for each of the memory segments in the first set of memory segments.

24. The memory device of claim 23, wherein the mode control circuitry is configured to generate two sets of control signals for the first set of memory segments, including a first set of control signals for the first mode of operation and a second set of control signals for the second mode of operation.

25. The memory device of claim 17, further comprising a number of data pins coupled to the storage array, wherein the number of data pins is equal to a number of simultaneously accessed data bits in the second mode of operation.

26. The memory device of claim 25, wherein at least one of the number of data pins is disabled in the first mode of operation.

* * * * *